

bond[®]



**Awarded As
MOST PROMISING BRAND**



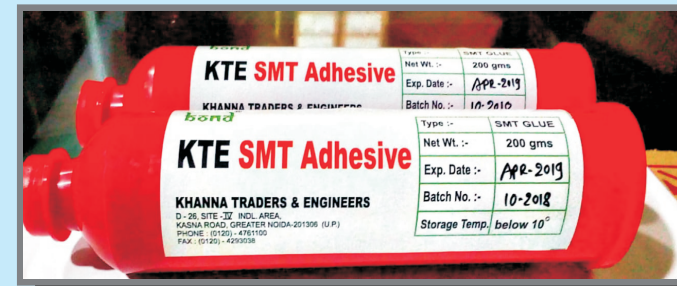
LEAD FREE SOLDER (ALL GRADES)



SOLDER STICKS, SOLDER WIRES, SOLDER PASTE & FLUXES (RMA, NO CLEAN, LOW SOLID AND LEAD FREE)



LEAD FREE SOLDER PASTE AND WIRES



SMT ADHESIVE



STATE OF THE ART R&D LAB



MAIN PRODUCTION UNIT AT GREATER NOIDA

Quality is our Identity

RANGE OF OUR PRODUCTS

METALS AND ALLOYS

- LEAD FREE SOLDER STICKS AND WIRES
- LEADED SOLDER STICKS AND WIRES
- SOLDER WIRES (SOLID, NO CLEAN, RMA, WATER SOLUBLE AND UREA BASED)
- ALUMINIUM SOLDER
- SILVER BRAZING RODS OF ALL GRADES
- TIN / ZINC WIRE
- SOLDER PREFORMS/FOILS
- TIN & SOLDER ANODES

FLUX AND SOLDERING CHEMICALS

- LEAD FREE FLUXES
- V.O.C FREE FLUXES
- RMA FLUXES
- NO CLEAN FLUXES
- WATER SOLUBLE FLUXES
- TINNING FLUXES
- ALUMINIUM FLUXES

SOLDER PASTE

- TIN / LEAD & LEAD FREE
- RMA / NO CLEAN
- SMT ADHESIVE

FLUX AND PCB CHEMICALS

- PCB CLEANING SOLVENTS
- PCB LACQUER
- COPPER LITE (COPPER CLEANING CHEMICALS)
- ANTI-OXIDENT (POWDER / METAL / OIL)
- HOT AIR LEVELLING FLUXES
- PCB INKS (PISM, THERMAL AND U.V.)
- U.V. SPOT COATING FOR PRINTING INDUSTRY

MANUFACTURED BY

KHANNA TRADERS & ENGINEERS

(AN ISO 9001:2015 & 14001:2015 CERTIFIED ORGANISATION)



HEAD OFFICE : -
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**KHANNA TRADERS
&
ENGINEERS**

(AN ISO 9001:2015 & 14001:2015 CERTIFIED ORGANISATION)

Manufacturers of :

- | |
|----------------|
| • SOLDERS |
| • FLUXES |
| • SOLDER PASTE |
| • SOLVENTS |
| • SMT ADHESIVE |

HEAD OFFICE

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website : www.bondsolder.in

KHANNA TRADERS & ENGINEERS

RANGE OF SOLDER PASTE IN PARTNERSHIP
WITH NIHON GENMA JAPAN

LEAD FREE SOLDER PASTE

Properties	SAC 305	Low Melting Point	Economical Version
Alloy Composition	Sn/Ag3.0/Cu0.5	Sn/Bi57/Ag1.0	Sn/Ag0.3/Cu0.5/Bi
Melting Point (°C)	217-221	139-141	207-224
Particle Size	22-38 & 22-45	22-38 & 22-45	22-38
Shape	Spherical	Spherical	Spherical
Flux Contents	11.5±0.3	10.0±0.3	11.5±0.3
Viscosity	200±20	190±20	200±20
Spreading	75% Minimum	75% Minimum	75% Minimum
Copper Corrosion Test	Passed	Passed	Passed
Shelf Life	1 Year	6 Months	1 Year

LEADED SOLDER PASTE

Properties	Sn 63	Sn/Pb/Ag2	Sn/Pb/Ag0.4
Alloy Composition	Sn63/Pb37	Sn62/Pb36/Ag2.0	Sn63/Pb36.6/Ag0.40
Melting Point (°C)	183-184	179-190	179-190
Particle Size	22-38 & 22-45	22-38 & 22-45	22-38 & 22-45
Shape	Spherical	Spherical	Spherical
Flux Contents	9.5±0.3	9.5±0.3	9.5±0.3
Viscosity	190±20	190±20	190±20
Spreading	90% Minimum	90% Minimum	90% Minimum
Copper Corrosion Test	Passed	Passed	Passed
Shelf Life	6 Months	6 Months	6 Months

ECONOMY THROUGH :

- ✦ **Outstanding storage stability** : Cosmo series can be stored at room temperature for three months (below 35°C)
- ✦ **Excellent stability in continuous printing** : It gives an excellent, continuous and stable printability for one week even for fine pitch of 0.3 mm.
 - Further more, it is still stable after being interrupted by long break.
 - No solder ball occurs after long hours of continuous printing.
 - Even after stopping the line for one hour, the print quality is stable from the first point.
 - No change in viscosity even at normal room temperature
- ✦ **Durable high tackiness performance** : Sufficient tackiness performance is obtained till 24 hours after the printing. Mounting accuracy of the components is improved.
- ✦ **Excellent durability against preheat slumping** : There is no slump at preheat temperature of 150-160°C. No solder balls and no bridging at QFPs.

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Properties	SAC 305	Low Melting Point	Economical Version
Alloy Composition	Sn/Ag3.0/Cu0.5	Sn/Bi57/Ag1.0	Sn/Ag0.3/Cu0.5/Bi
Melting Point (°C)	217-221	139-141	207-224
Particle Size	22-38 & 22-45	22-38 & 22-45	22-38
Shape	Spherical	Spherical	Spherical
Flux Contents	11.5±0.3	10.0±0.3	11.5±0.3
Viscosity	200±20	190±20	200±20
Spreading	75% Minimum	75% Minimum	75% Minimum
Copper Corrosion Test	Passed	Passed	Passed
Shelf Life	1 Year	6 Months	1 Year

LEADED SOLDER PASTE

Properties	Sn 63	Sn/Pb/Ag2	Sn/Pb/Ag0.4
Alloy Composition	Sn63/Pb37	Sn62/Pb36/Ag2.0	Sn63/Pb36.6/Ag0.40
Melting Point (°C)	183-184	179-190	179-190
Particle Size	22-38 & 22-45	22-38 & 22-45	22-38 & 22-45
Shape	Spherical	Spherical	Spherical
Flux Contents	9.5±0.3	9.5±0.3	9.5±0.3
Viscosity	190±20	190±20	190±20
Spreading	90% Minimum	90% Minimum	90% Minimum
Copper Corrosion Test	Passed	Passed	Passed
Shelf Life	6 Months	6 Months	6 Months

ECONOMY THROUGH :

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